SLLS130C - SEPTEMBER 1991 - REVISED MAY 1995

- Single IC and Single 5-V Supply Interface for Serial Communication Ports
- Meets or Exceeds the Requirements of ANSI Standards EIA/TIA-232-E-1991, EIA/TIA-562, and ITU Recommendation V.28
- Switched-Capacitor Voltage Converter Eliminates Need for ±12-V Supplies
- Voltage Converter Operates With Low Capacitance . . . 0.1 μF Min
- Designed for Data Rates up to 120 kb/s Over 3-m Cable
- Available in Shrink Small-Outline 25-mil-Pitch Package
- Shutdown Mode to Save Power When Not in Use
- ±30-V Receiver Input Voltage Range
- LinBiCMOS™ Process Technology
- Applications
  - Laptop or Notebook Computers
  - Portable Terminals
  - Single-Board Computers
  - Portable Test Equipment

## DB PACKAGE (TOP VIEW)



NC-No internal connection

## description

The SN75LBC187 is a low-power LinBiCMOS™ device containing three drivers, five receivers, and a switched-capacitor voltage converter. The SN75LBC187 provides a single chip and single 5-V supply interface between the asynchronous communications element and the serial port connector of the data terminal equipment (DTE). This device has been designed to conform to ANSI Standards EIA/TIA-232-E, EIA/TIA-562, and ITU recommendation V.28.

The switched-capacitor voltage converter of the SN75LBC187 uses four small external capacitors to generate the positive and negative voltages required by EIA/TIA-232-E (and V.28) line drivers from a single 5-V input. The drivers feature output slew-rate limiting to eliminate the need for external filter capacitors. The receivers can accept  $\pm 30$  V without damage. The device also features a reduced power or shutdown mode that cuts the quiescent power to the IC when not transmitting data between the CPU and peripheral.

The SN75LBC187 has been designed using LinBiCMOS™ technology and cells contained in the Texas Instruments LinASIC™ library. The SN75LBC187 is characterized for operation from 0°C to 70°C.

#### NOTE:

This device includes circuit designs and process technologies that have patents pending.



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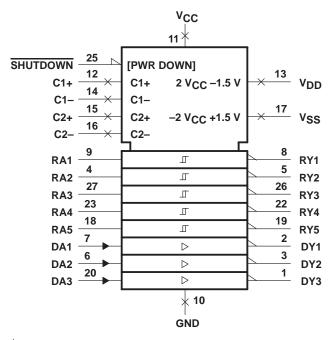
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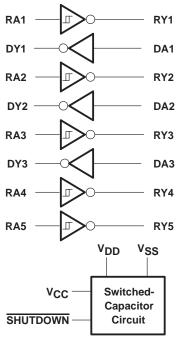


SLLS130C – SEPTEMBER 1991 – REVISED MAY 1995

## logic symbol<sup>†</sup>

# logic diagram (positive logic)





## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub> (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V <sub>DD</sub>	V <sub>CC</sub> -0.3 V to 15 V
Negative output supply voltage range, VSS	0.3 V to –15 V
Input voltage range, V <sub>I</sub> : RA	±30 V
All other inputs	0.3 V to V <sub>CC</sub> + 3 V
Output voltage range, V <sub>O</sub> : DY	$-2 V_{CC} + 1.2 V$ to $2 V_{CC} - 1.2 V$
All other outputs	$\dots \dots $
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stq</sub>	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

<sup>\$</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages are with respect to the network ground terminal.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING
DB	1025 mW	8.2 mW/°C	656 mW



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

## recommended operating conditions

			NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>			5	5.5	V
High-level input voltage, V <sub>IH</sub>	DA	2			V
	RA, SHUTDOWN	2.4			V
Low-level input voltage, V <sub>IL</sub>	RA, DA, SHUTDOWN			0.8	V
Receiver input voltage, V <sub>I</sub>				25	V
High-level output current, IOH	RY			-1	mA
Low-level output current, IOL	RY			3.2	mA
Output current, IO	$V_{DD}$			±10	μΑ
	V <sub>SS</sub>			±10	μΑ
C1, C2, C3, C4 charge pump capacitors		0.1	0.47		μF
Operating free-air temperature, TA		0		70	°C

## electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT		
VOH High-level output voltage		Receiver	$I_O = -1 \text{ mA}$	= –1 mA 3.5				V	
		Driver	$R_L = 3 \text{ k}\Omega \text{ to GN}$	D	5	7		V	
V - Low level output voltage		Receiver	$I_O = 3.2 \text{ mA}$				0.4	-l V I	
V <sub>OL</sub> Low-level output voltage	Driver	$R_L = 3 \text{ k}\Omega \text{ to GN}$	D		-7	-5			
V <sub>IT+</sub> Receiver positive-going input voltage threshold					1.7	2.4	V		
V <sub>IT</sub> Receiver negative-going input voltage threshold				0.8	1.2		V		
V <sub>hys</sub> Receiver input hysteresis voltage (V <sub>IT+</sub> – V <sub>IT-</sub> )					0.5	1	V		
rį	Receiver input resistance		$V_{CC} = 5 V$ ,	T <sub>A</sub> = 25°C	3	5	7	kΩ	
ro	Driver output resistance		$V_{CC} = 0$ ,	V <sub>O</sub> = ±2 V	300			Ω	
I <sub>I</sub> Input current (DA, SHUTDOWN)		$V_I = 0$ to $V_{CC}$				±50	μΑ		
los	Driver output short-circuit current		V <sub>O</sub> = 0		±10			mA	
Icc	Supply current	Normal operation	All outputs open,	SHUTDOWN at 2.4 V		15	30	mA	
		Shutdown mode	All outputs open,	SHUTDOWN at 0.1 V			10	μΑ	

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$  and  $T_A = 25^{\circ}\text{C}$ .



## SN75LBC187 MULTICHANNEL EIA-232 DRIVER/RECEIVER WITH CHARGE PUMP

SLLS130C - SEPTEMBER 1991 - REVISED MAY 1995

## switching characteristics over recommended operating conditions, $T_A = 25^{\circ}C$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT	
tpLH Propagation delay time, low- to high-level o	Decreasing delegations law to bigh level output	Receiver	$R_L = 5 k\Omega$ , See Figure 1	C <sub>L</sub> = 50 pF,		1.25	μs
	Propagation delay time, low- to high-level output	Driver	$R_L = 3 kΩ$ , See Figure 2	C <sub>L</sub> = 1200 pF,		1.25	μs
tpHL Propagation delay time, high- to low-leve	Drangation delay time high to law layer output	Receiver	$R_L = 5 k\Omega$ , See Figure 1	$C_L = 50 \text{ pF},$		1.25	μs
	Propagation delay time, mgn- to low-level output	Driver	$R_L = 3 kΩ$ , See Figure 2	C <sub>L</sub> = 1200 pF,		1.25	μs
t <sub>r</sub> Rise time, driver output			$R_L = 3 \text{ k}\Omega,$ $V_O = -3 \text{ V to 3 V},$	C <sub>L</sub> = 50 pF, See Note 2	200		ns
			$R_L = 3 \text{ k}\Omega,$ VO = -3.3 V to 3.3 V,			1.5	μs
t <sub>f</sub> Fall time, driver output		$R_L = 3 \text{ k}\Omega$ , $V_O = 3 \text{ V to } -3 \text{ V}$	$C_L = 50 \text{ pF},$	200		ns	
			$R_L = 3 \text{ k}\Omega,$ $V_O = 3.3 \text{ V to } -3.3 \text{ V}$	C <sub>L</sub> = 2500 pF,		1.5	μs

NOTES: 2. The 200 ns for the output to change from -3 V to 3 V (or vice versa) corresponds to the 30 V/ $\mu$ s maximum slew rate of EIA/TIA-232-E, EIA/TIA-562, and ITU Recommendation V.28.



<sup>3.</sup> The more stringent requirement for transition times comes from the EIA/TIA-562, which requires the rise and fall times to be measured from 3.3 V.

## PARAMETER MEASUREMENT INFORMATION

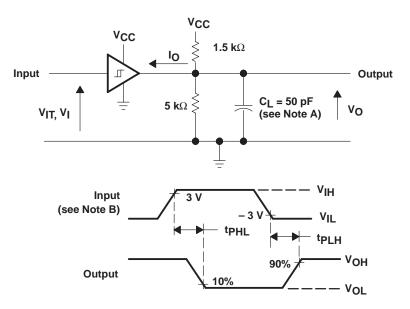
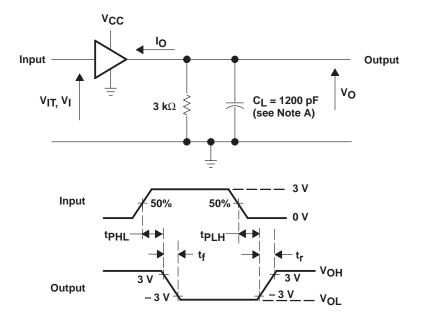


Figure 1. Receiver Test Circuit and Waveforms



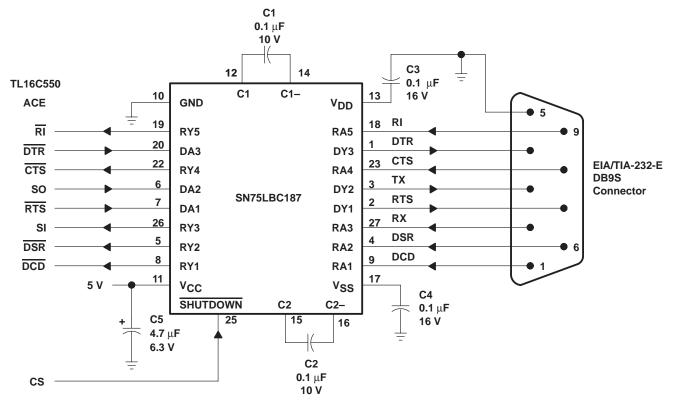
NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $t_W = 8.33 \mu s$ , PRR = 60 kHz,  $t_\Gamma = t_f \le 50 ns$ .

Figure 2. Driver Test Circuit and Waveforms

SLLS130C - SEPTEMBER 1991 - REVISED MAY 1995

### **APPLICATION INFORMATION**



NOTE: C1, C2, C3, and C4 are Z5U-type ceramic-chip capacitors.

Figure 3. Typical SN75LBC187 Connection



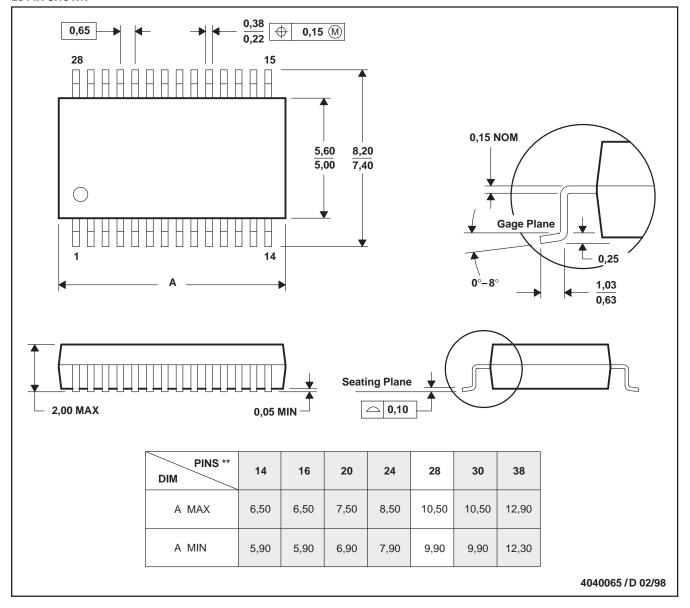
SLLS130C - SEPTEMBER 1991 - REVISED MAY 1995

## **MECHANICAL DATA**

## DB (R-PDSO-G\*\*)

#### 28 PIN SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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